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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/814,809	04/01/2004	Dawn Melman	044499-0200	5310

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EXAMINER	
NGUYEN, HOANG V	
ART UNIT	**PAPER NUMBER**
2821	

DATE MAILED: 01/17/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)	
	10/814,809	MELMAN, DAWN	
	Examiner	Art Unit	
	Hoang V. Nguyen	2821	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☐ Responsive to communication(s) filed on _____.

2a)☐ This action is **FINAL**. 2b)☒ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) 1-20 is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☒ Claim(s) 1-20 is/are rejected.

7)☐ Claim(s) _____ is/are objected to.

8)☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☐ The drawing(s) filed on _____ is/are: a)☐ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☐ All b)☐ Some * c)☐ None of:

1.☐ Certified copies of the priority documents have been received.

2.☐ Certified copies of the priority documents have been received in Application No. _____.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☒ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____.
4) ☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application (PTO-152)
6) ☐ Other: _____.

Allowable Subject Matter

1. The indicated allowability of claims 15-20 is withdrawn in view of the newly discovered reference(s) to Mariotti et al (EP 1 071 158 A2). Rejections based on the newly cited reference(s) follow.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

> A person shall be entitled to a patent unless –
>
> (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

3. Claims 1-20 are rejected under 35 U.S.C. 102(b) as being anticipated by Mariotti et al (EP 1 071 158 A2).

Regarding claim 1, the device of Mariotti (Figures 2A-2E) would enable the method of making a device comprising the steps of winding a coil 40; disposing the coil in a predetermined position on a component 30 which forms part of the device; connecting the ends of the coil to first and second pins 36 by winding the ends of the coil onto the pins; and disposing the first and second pins in electrical connection with first and second connection structures (not numbered) formed on a printed circuit board 50 which is disposed on the component.

Regarding claim 2, as applied to claim 1, Figure 2A of Mariotti shows that a first end of a wire used to form the coil is wound onto the first pin before the wire is wound into the coil.

Regarding claim 3, as applied to claim 1, Figure 2A of Mariotti shows that the component 30 is a molded body and wherein the steps of disposing the coil 40, connecting the ends of the coil to the first and second pins 36 and the step of disposing the first and second pins

in the first and second connecting structure, are all carried out in absence of overmolding of any part of the coil once disposed on the molded body.

Regarding claim 4, as applied to claim 1, it is inherent that the ends of the coils are soldered to the pins.

Regarding claim 5, as applied to claim 1, it is inherent that the pins can be soldered to the connection structures of the PCB.

Regarding claim 6, as applied to claim 5, Figure 2D of Mariotti would enable the step of soldering the ends of the coils to the pins and the step of soldering the pins to the connection structures on the PCB are being carried out after the ends of the coil have been wound on the pins and the pins have been disposed in position with respect to the PCB so that the pins are in contact with the connection sites.

Regarding claim 7, as applied to claim 1, Figure 2A of Mariotti would enable the step of winding the coil 40 on the bobbin 32 which is separate from the component.

Regarding claim 8, as applied to claim 1, Figure 2A of Mariotti shows that the component 30 is a molded body.

Regarding claim 9, as applied to claim 1, Mariotti (abstract) teaches that the vehicle is an automotive vehicle.

Regarding claim 10, the coil structure of Mariotti (Figures 2A-2E) would enable the method of making a device comprising winding an antenna coil 40; connecting a first end of the coil to a first pin 36; disposing the coil in a predetermined position on a component 30 which forms part of the device; connecting a second end of the coil to the second pin 36; disposing the first pin in a first predetermined position on a PCB which is disposed in the device with the

component; and disposing the second pin in a second predetermined connection position on the PCB 50.

Regarding claim 11, as applied to claim 10, Figure 2A of Mariotti would enable the step of winding the coil 40 being carried out on a form 30 and disposed in the device and wherein the step of connecting the first end of the coil to the first pin 36; connecting the second end of the coil to the second pin 36; disposing the first pin in the predetermined position and the step of disposing the second pin in the second predetermined connection position are carried out in absence of a molding process wherein the coil is overmolded.

Regarding claim 12, as applied to claim 11, Figure 2A of Mariotti shows that the form is a bobbin 30.

Regarding claim 13, as applied to claim 10, Figure 2A of Mariotti would enable the step of connecting the ends of the coil to the first and second pins 36 by winding the ends of the coil 40 onto the first and second pins; and disposing the first and second pins in the connection positions further comprises soldering the first and second coil ends to the first and second pins and soldering the first and second pins to electrical connection structures associated with the first and second connection positions.

Regarding claim 14, as applied to claim 10, Figure 2A of Mariotti would enable the step of soldering the first and second coil ends to the first and second pins and the soldering of the first and second pins to the first and second connection sites being carried out while the pins are *in situ* in the first and second connection sites.

Regarding claim 15, the device of Mariotti (Figures 2A-2D) would enable the method of making a device comprising the steps of molding first and second components 20 and 30;

forming an antenna coil 40; disposing the antenna coil on the first component 30 without overmolding the coil; disposing a printed circuit board 50 on one of the first and second components; connecting the first and second ends of the coil to the PCB to establish first and second electrical connections between the coil and the PCB; and coupling the first and second components together to enclose the non-overmolded coil.

Regarding claim 16, as applied to claim 15, Figure 2A of Mariotti would enable the steps of winding a first end of the coil on the first pin 36; winding the second end of the coil on a second pin 36; disposing the first pin in a first predetermined position on the PCB; disposing the second pin in a second predetermined position on the PCB; soldering the first end of the coil to the first pin; soldering the second end of the coil to the second pin; soldering the first pin to a first connection structure on the PCB; and soldering the second pin to a second connection structure on the PCB.

Regarding claim 17, Mariotti (Figures 2A-2E) discloses a device comprising first and second molded components 20 and 30; a non-overmolded antenna coil 40 which is disposed on one of the first and second molded components; a printed circuit board 50 disposed with one of the first and second components and connected to the antenna coil via first and second pins 36 which respectively have first and second ends of the coil wound therearound and soldered thereto, and wherein the first and second pins are soldered to first and second connection structures on the PCB.

Regarding claim 18, as applied to claim 17, Figure 2C of Mariotti shows that the first and second molded components 20 and 30 couple together to enclose the non-over molded antenna coil 40.

Regarding claim 19, as applied to claim 18, Figure 2E shows that the PCB is enclosed by the intercooler first and second molded components.

Regarding claim 20, as applied to claim 17, Mariotti (abstract) teaches that the device comprises an antitheft device for an automotive vehicle.

Inquiry

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hoang V. Nguyen whose telephone number is (571) 272-1825. The examiner can normally be reached on Mondays-Fridays from 8:00 a.m. to 4:00 p.m..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Don Wong can be reached on (571) 272-1834. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

5. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Hvn
1/12/06

HOANG V. NGUYEN
PRIMARY EXAMINER